

Title (en)

PRETREATMENT METHOD FOR PRETREATING COMPONENTS PRIOR TO ELECTROPLATING

Title (de)

VORBEHANDLUNGSVERFAHREN ZUM VORBEHANDELN VON BAUTEILEN VOR EINEM GALVANISCHEN BESCHICHTEN

Title (fr)

PROCÉDÉ DE PRÉTRAITEMENT POUR LE PRÉTRAITEMENT DE COMPOSANTS AVANT UN REVÊTEMENT GALVANIQUE

Publication

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Application

EP 20713239 A 20200318

Priority

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Abstract (en)

[origin: WO2020193307A1] The invention relates to a pretreatment method (A) for pretreating components (10), which are each formed from at least two different materials, prior to coating. The pretreatment method (A) comprises the following steps: alkaline degreasing (1); chemical pickling (2) in a first pickling medium; anodic pickling (3) in a second pickling medium; and cathodic degreasing (4).

IPC 8 full level

C25D 5/36 (2006.01); **C25D 7/00** (2006.01); **C25D 7/04** (2006.01); **C25F 1/06** (2006.01); **H01T 13/00** (2006.01); **H01T 21/00** (2006.01)

CPC (source: EP US)

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Citation (search report)

See references of WO 2020193307A1

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